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MATERIALS SCIENCE AND ENGINEERING

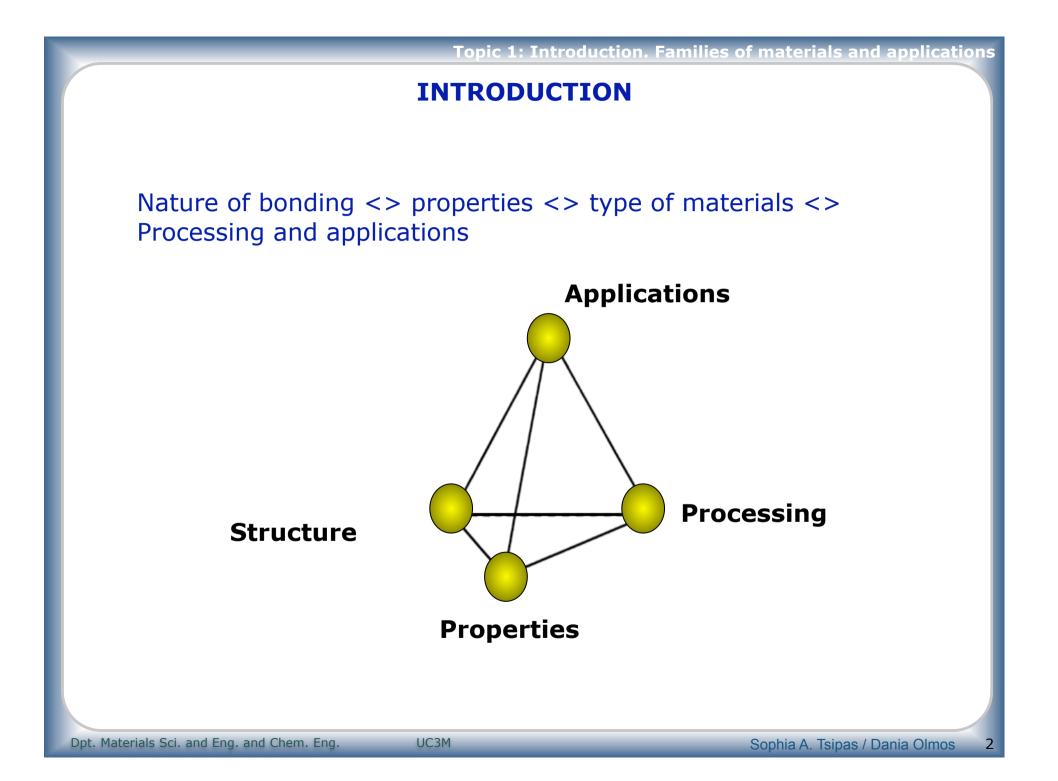
TOPIC 1.2. BONDING IN SOLIDS. RELATION BETWEEN BONDING, STRUCTURE AND PROPERTIES OF MATERIALS

Introduction

• Bonding in solids

- Ionic bond
- Covalent bond
- Metallic bond
- Intermolecular forces

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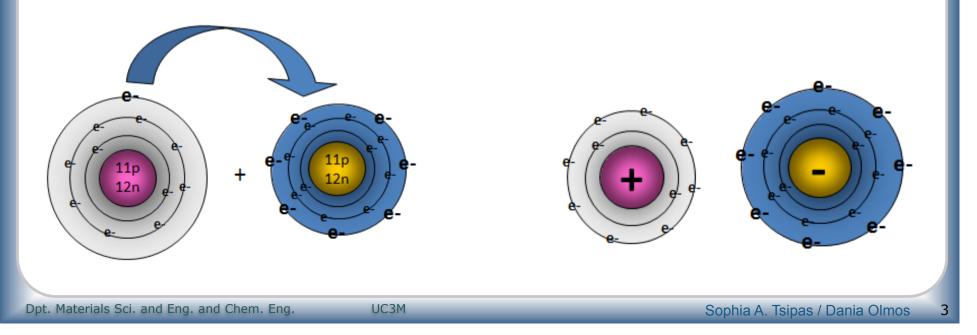
IONIC BOND

It forms between a metal and a non metal.

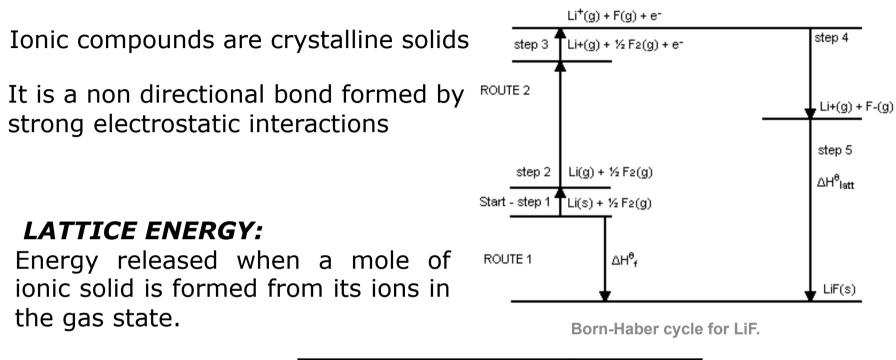
There is electron transfer from the less electronegative atom to the more electronegative .

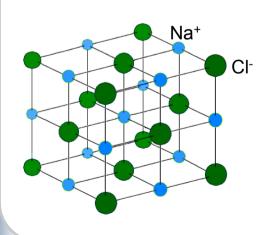
Bonding forces \Rightarrow F electrostatic attraction between opposite charged ions.

- Pure ionic bond: ideal.
- \Rightarrow Always exists covalent participation



IONIC BOND





Step	∆H(kJ/mol)
Sublimation of Li	155.2
Dissociation of $F_{2(g)}$	150.6
Ionization of Li _(g)	520
Gain of e^{-} of $F_{(g)}$	-328
Formation of LiF from $Li_{(s)}$ and $\frac{1}{2}F_{2(g)}$	-594.1

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IONIC BOND

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LATTICE ENERGY:

Many properties are dependent on the lattice energy (melting point, hardness, thermal expansion coefficient)

lonic Solids	Lattice Energies (kJ/mol)	Melting point (°C)
LiCl	-829	613
NaCl	-766	801
KCI	-686	776
RbCl	-670	715
CsCl	-649	646
MgO	-3932	2800
CaO	-3583	2580
SrO	-3311	2430
BaO	-3127	1923

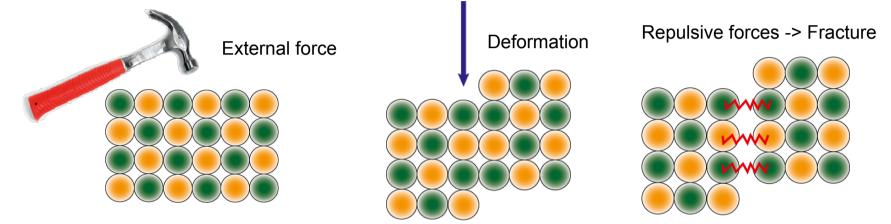
When the ion size $\uparrow \Rightarrow$ lattice energy \downarrow and $T_f \downarrow$ Valence +1

Valence +2 $\begin{array}{l} \mbox{Valence +2} \\ \mbox{Valance number } \uparrow \ \Rightarrow \mbox{lattice} \\ \mbox{energy } \uparrow \Rightarrow T_f \uparrow \end{array}$

IONIC BOND

General properties of ionic compounds

Strong electrostatic attraction \rightarrow High melting and evaporation points Hard and brittle solids at room temperature



They do not conduct electricity (except in molten state or when dissolved in water)

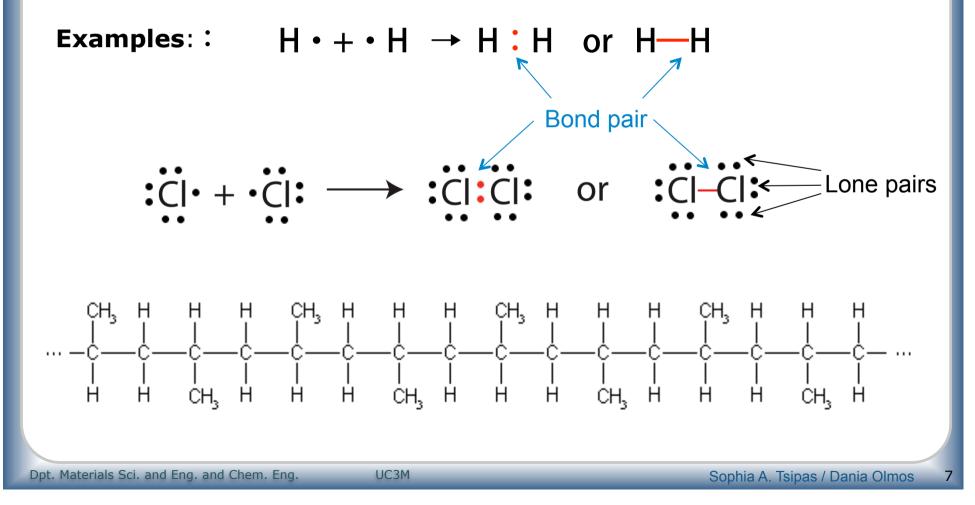
Water soluble.

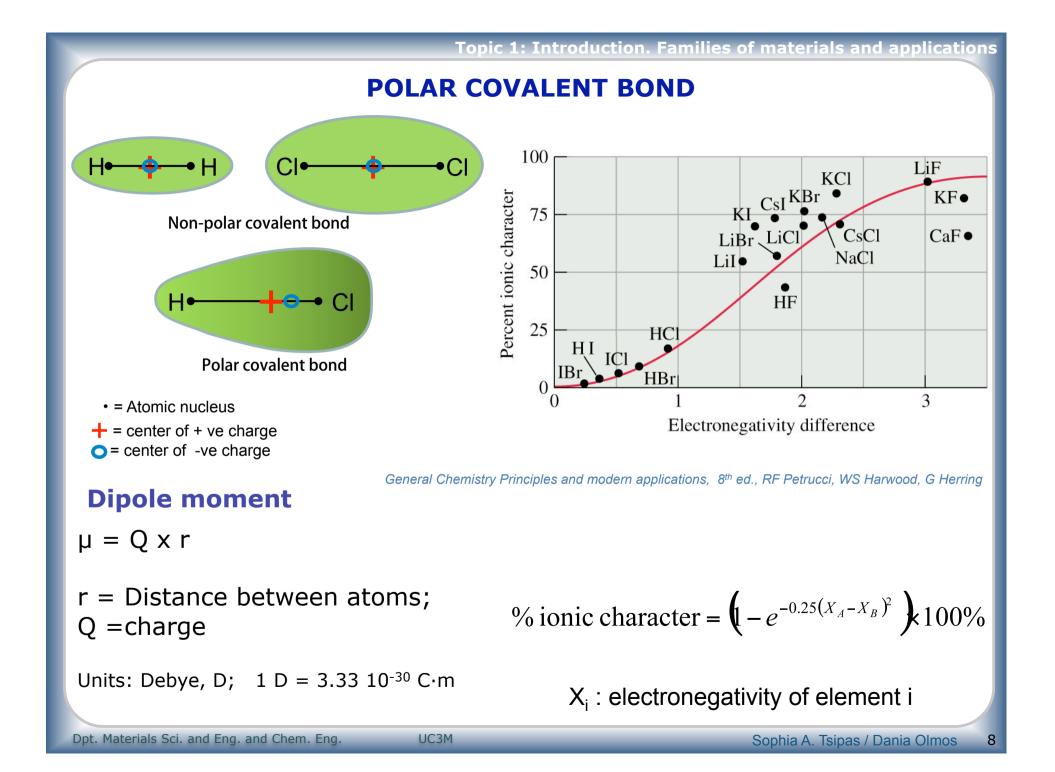
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COVALENT BOND

Generally it forms between the non metallic elements of the periodic table

It forms by electron sharing



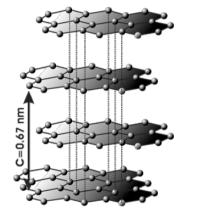


COVALENT BOND

• Properties of the compounds with covalent bonds

Covalent Solids

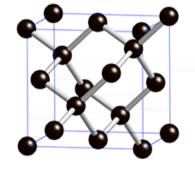
Formed by a system of continuous covalent bonds Non conductive LATTICES both in the solid and in the molten state Diamond, boron nitride, quartz (SiO₂), silicon carbide (SiC)



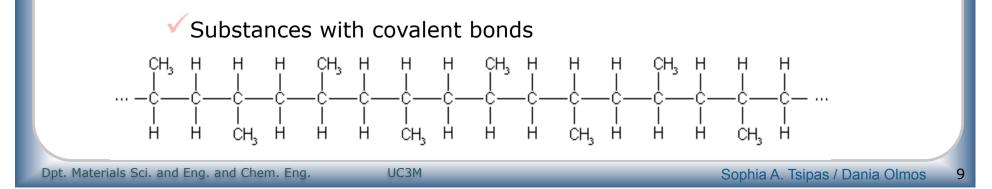
Hard and incompressible
T_f high, non volatile
insoluble

graphite

http://commons.wikimedia.org/wiki/File:Graphit_gitter.png

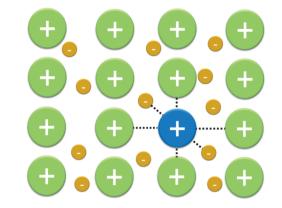


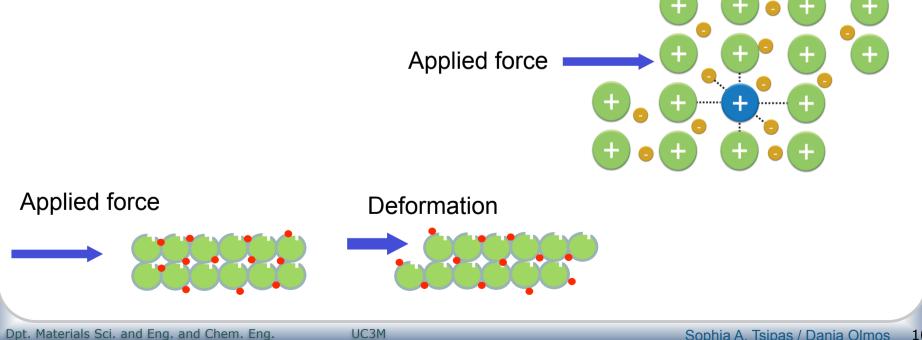
Diamond

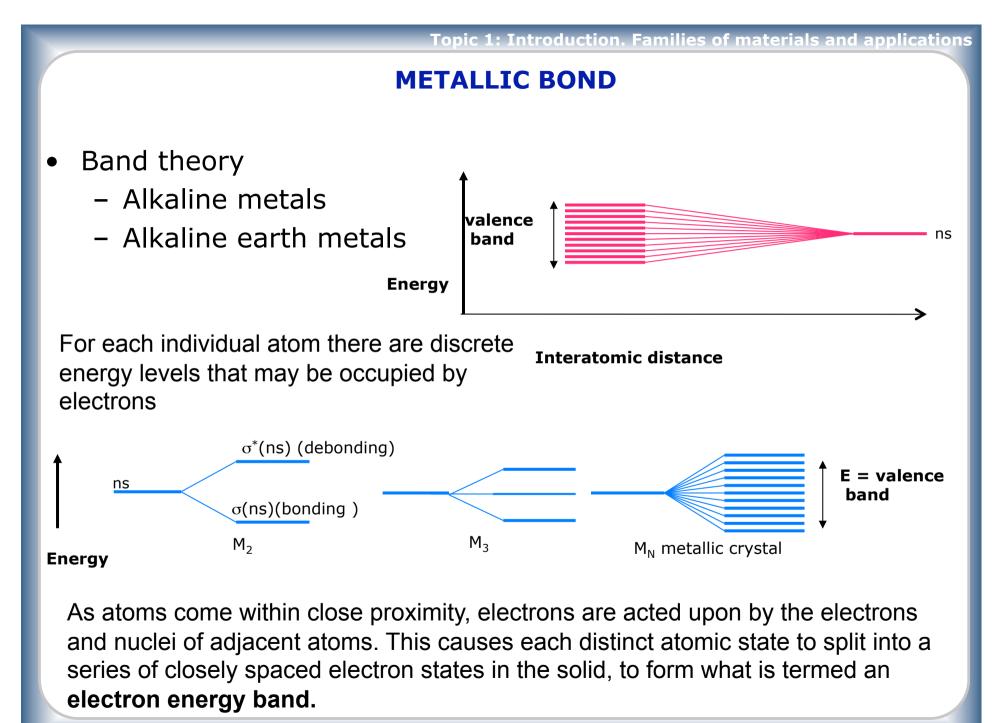


METALLIC BONDS

- Model of a sea of electrons
 - Atomic nucleus surrounded from a sea of e^{-} .
 - Metallic shine .
 - Workability.





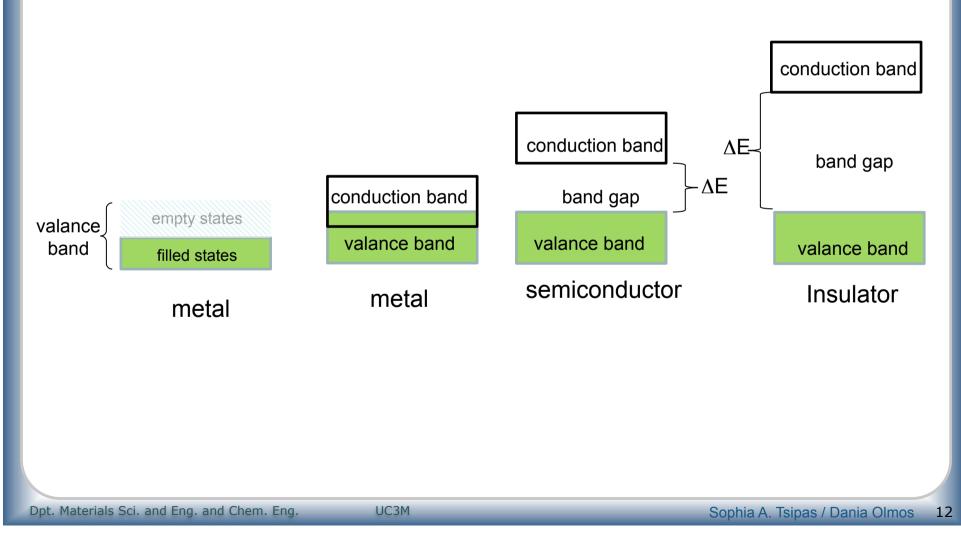


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METALLIC BOND

The number of electrons available for electrical conduction in a particular material is related to the arrangement of electron states with respect to energy, and then the manner in which these states are occupied by electrons.



INTERMOLECULAR FORCES

Primary bonds: (strong)

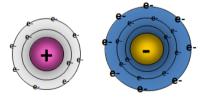
-Ionic bond:Transfer of $e^- \Rightarrow$ cations and anions $\Rightarrow F_{coulomb}$ (non
directional)

Sharing e⁻ (directional)

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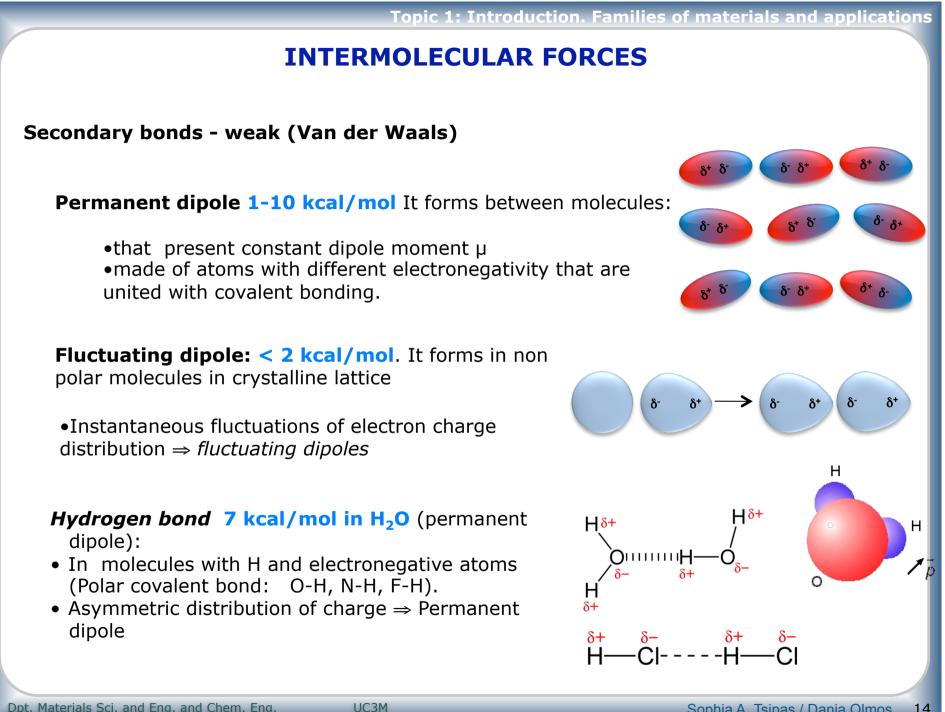
- Covalent bond: (>50-150 kcal/mol)
- Metallic bond: (>20-120 kcal/mol)

e- shared externally and very little tightened by the nucleus (non directional)



:Cl.+:Cl.→:Cl:Cl:





BONDING AND PROPERTIES

Bond	Type of substance	Melting and boiling points	Mechanical properties	Solubility
COVALENT	Molecular	Low	Soft in the solid state	Depends on the polarity of the molecules
COVALENT	Atomic, covalent or lattice	Very high	Very hard brittle	Insoluble in all solvents
IONIC	Ionic	High	Hard and brittle	Soluble in polar solvents
METALLIC	Metallic	High	Ductile and workable	Insoluble in all solvents

GENERAL PROPERTIES OF MATERIALS

Nature of bonding ↔ properties ↔ type of materials

Type of material	Character of bonding	Examples	
Metal	Metallic	Fe, steels	
Ceramic and glasses	Ionic/ covalent	Silica (SiO ₂)	
Polymers	Covalent and secondary	Polyethylene –(CH_2)-	

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